



December 28, 2017

Company name: RS Technologies Co.,Ltd.

Representative: Nagayoshi HO, President & CEO

Listing: Tokyo Stock Exchange (1st)

Stock code: 3445

Contact: Masayuki Suzuki, CFO

Tel: +81-3-5709-7685

Announcement of the capacity increase for 300mm silicon wafer reclaim

RS group decided to increase the reclaim capacity of 300mm silicon wafer up to 400k/month in order to meet the expanding demand in the medium term today.

This decision is to support our customer's active new construction or expansion of 300mm line as the leading company of silicon wafer reclaim.

This investment enable us to reclaim wafers with metallic circuit on it's surface.

Our technology of removing metal contamination from the wafer is acknowledged by our major customers.

We succeeded in finding the potential market demand and are accepting the expecting newly coming up demand.

1. Details of the Capital Investment

(1) Location	RS Technologies Sanbongi Factory : 26-2, Yamazaki, Sanbongi Otonashi, Osaki, Miyagi 989-6313 JAPAN RSTEC Semiconductor Taiwan Co., LTD. Tainan Factory : No.1,Nanke 7 th Rd.,Southern Taiwan Science Park,Tainan City, Taiwan
(2) Project investment amount	1.1billion (RS Technologies Sanbongi Factory 0.4 billion, RSTEC Semiconductor Taiwan Co., LTD. 0.7 billion)
(3) Funds procurement method	Own Cash
(4) Scheduled start of Operations	First half of 2019

2. capacity increase for 300mm silicon wafer reclaim

Company name	RS Technologies	RSTEC Semiconductor Taiwan	Amount
Capacity	20,000 wafers a month	30,000 wafers a month	50,000 wafers a month

3. Future Outlook

This capital investment will have no effect on the Company's current and next term business performance.